ASSOCIATION CONNECTING	© Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved u ntions.	nder both	This docum level parts, t	ent is a declarat	ion of the s encompasse	ubstances v s all lower	within the manufactur elevel materials for w	rer listed	item. Note: if nanufacturer	the item is an as has engineering	ssembly with lower responsibility.
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				als and Mfg Information				
Supplier Inform	ation													
Company name* Con			Company uni	Company unique ID			Unique ID Authority				Response Date*			
onsemi											2025-06-06			
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Ti			Title - Repres	Title - Representative			Phone - Representative*				Email - Representative*			
Product-Env-Stewa	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requester	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Date Version Manufacturing Site			Weight*	UOM	Unit Type	
		SS16FP 60V		60V 1A Schottky Rectif		2025-06-06		Т	TSCBE		21.80046	mg	Each	
Manufacturing l	Proccess Information	n											•	
Terminal Plating / Grid Array Material Termin			erminal Base A	al Base Alloy J-STD-020 MSL R			Peak Process Body Temperature Max Time at Pe			e Max Time at Peak	k Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed CU Alloy			U Alloy	1	l .		260		С	30	seco	nds 3		
Comments														
evel 1 - maximum ti	me at peak temperature o	during sol	dering is 10-3	0 seconds										
For more informatio	n regarding material con	position	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	1.3299	mg	Supplier	Iron (Fe)	7439-89-6		0.0013	mg
			Supplier	Copper (Cu)	7440-50-8		1.3282	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0004	mg
Die	2.022	mg	Supplier	Titanium (Ti)	7440-32-6		0.003	mg
			Supplier	Silver (Ag)	7440-22-4		0.0752	mg
			Supplier	Silicon (Si)	7440-21-3		1.9251	mg
			В	Nickel (Ni)	7440-02-0		0.0186	mg
Die Attach Solder	0.41096	mg	Supplier	Silver (Ag)	7440-22-4		0.0103	mg
			А	Lead (Pb)	7439-92-1	7a	0.3801	mg
			Supplier	Tin (Sn)	7440-31-5		0.0205	mg
Lead Frame	12.3086	mg	Supplier	Iron (Fe)	7439-89-6		0.0123	mg
			Supplier	Copper (Cu)	7440-50-8		12.2926	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Mold Compound-Black	5.7288	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5757	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0286	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.8953	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.2292	mg
Plating	2.0E-4	mg	Supplier	Tin (Sn)	7440-31-5		0.0002	mg